

Optocoupler, Photodarlington Output, High Gain

Features

- Extra low coupling capacity - typical 0.2 pF
- High Common Mode Rejection
- Available in single or four channels
- Lead-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC

Agency Approvals

- UL1577, File No. E76222 System Code U, Double Protection
- CSA 22.2 bulletin 5A, Double Protection
- BSI IEC60950 IEC60065
- DIN EN 60747-5-2 (VDE0884)
DIN EN 60747-5-5 pending
- FIMKO

Applications

Switch-mode power supplies

Line receiver

Computer peripheral interface

Microprocessor system interface

Reinforced Isolation provides circuit protection against electrical shock (Safety Class II)

Circuits for safe protective separation against electrical shock according to safety class II (reinforced isolation):

- For appl. class I - IV at mains voltage ≤ 300 V
- For appl. class I - III at mains voltage ≤ 600 V according to DIN EN 60747-5-2(VDE0884)/ DIN EN 60747-5-5 pending, table 2, suitable for.

Description

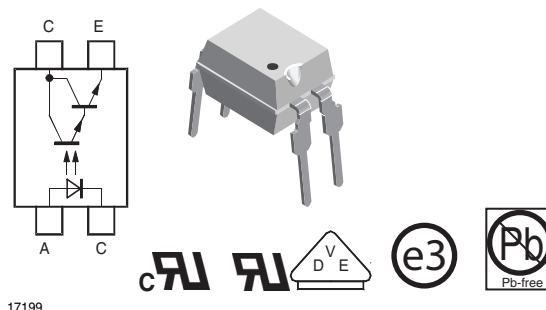
The TCED1100 consists of a phototransistor optically coupled to a gallium arsenide infrared-emitting diode in a 4-lead up to 16-lead plastic dual inline package.

The elements are mounted on one leadframe providing a fixed distance between input and output for highest safety requirements.

Safety for mains-operated electronic and related household apparatus

Rated impulse voltage (transient overvoltage)

$V_{IOTM} = 8$ kV peak



17199

Isolation test voltage (partial discharge test voltage)

$V_{pd} = 1.6$ kV

Rated isolation voltage (RMS includes DC)

$V_{IOWM} = 600$ V_{RMS} (848 V peak)

Rated recurring peak voltage (repetitive)

$V_{IORM} = 600$ V_{RMS}

Thickness through insulation ≥ 0.75 mm

Internal creepage distance > 4 mm

Creepage current resistance according to VDE 0303/ IEC 60112 Comparative Tracking Index:

CTI ≥ 175

VDE Standards

These couplers perform safety functions according to the following equipment standards:

DIN EN 60747-5-2(VDE0884)/ DIN EN 60747-5-5 pending

Optocoupler for electrical safety requirements

IEC 60950/EN 60950

Office machines (applied for reinforced isolation for mains voltage ≤ 400 VRMS)

VDE 0804

Telecommunication apparatus and data processing

IEC 60065

Safety for mains-operated electronic and related household apparatus

Order Information

Part	Remarks
TCED1100	CTR 600 %, DIP-4
TCED1100G	CTR 600 %, DIP-4

G = Leadform 10.16 mm; G is not marked on the body

Absolute Maximum Ratings

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Stresses in excess of the absolute Maximum Ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute Maximum Rating for extended periods of the time can adversely affect reliability.

Input

Parameter	Test condition	Symbol	Value	Unit
Reverse voltage		V_R	6	V
Forward current		I_F	60	mA
Forward surge current	$t_p \leq 10\text{ }\mu\text{s}$	I_{FSM}	1.5	A
Power dissipation		P_{diss}	100	mW
Junction temperature		T_j	125	$^{\circ}\text{C}$

Output

Parameter	Test condition	Symbol	Value	Unit
Collector emitter voltage		V_{CEO}	35	V
Emitter collector voltage		V_{ECO}	7	V
Collector current		I_C	80	mA
Collector peak current	$t_p/T = 0.5$, $t_p \leq 10\text{ ms}$	I_{CM}	100	mA
Power dissipation		P_{diss}	150	mW
Junction temperature		T_j	125	$^{\circ}\text{C}$

Coupler

Parameter	Test condition	Symbol	Value	Unit
Isolation test voltage (RMS)	$t = 1\text{ min}$	V_{ISO}	5000	V_{RMS}
Total power dissipation		P_{tot}	250	mW
Operating ambient temperature range		T_{amb}	- 40 to + 100	$^{\circ}\text{C}$
Storage temperature range		T_{stg}	- 55 to + 125	$^{\circ}\text{C}$
Soldering temperature	2 mm from case $t \leq 10\text{ s}$	T_{sld}	260	$^{\circ}\text{C}$



Electrical Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

Input

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Forward voltage	$I_F = 20\text{ mA}$	V_F		1.15	1.4	V
Junction capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$	C_j		50		pF

Output

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Collector emitter voltage	$I_C = 1\text{ mA}$	V_{CEO}	32			V
Emitter collector voltage	$I_E = 100\text{ }\mu\text{A}$	V_{ECO}	7			V
Collector-emitter cut-off current	$V_{CE} = 10\text{ V}$, $I_F = 0$, $E = 0$	I_{CEO}		15	100	nA

Coupler

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Collector emitter saturation voltage	$I_F = 20\text{ mA}$, $I_C = 5\text{ mA}$	V_{CEsat}			1	V
Cut-off frequency	$V_{CE} = 5\text{ V}$, $I_F = 10\text{ mA}$, $R_L = 100\text{ }\Omega$	f_c		10		kHz
Coupling capacitance	$f = 1\text{ MHz}$	C_k		0.3		pF

Current Transfer Ratio

Parameter	Test condition	Part	Symbol	Min	Typ.	Max	Unit
I_C/I_F	$V_{CE} = 2\text{ V}$, $I_F = 1\text{ mA}$	TCED1100	CTR	6.0	8.0		%

Maximum Safety Ratings

(according to DIN EN 60747-5-2(VDE0884)/ DIN EN 60747-5-5 pending) see figure 1

This optocoupler is suitable for safe electrical isolation only within the safety ratings.

Compliance with the safety ratings shall be ensured by means of suitable protective circuits.

Input

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Forward current		I_F			130	mA

Output

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Power dissipation		P_{diss}			265	mW

Coupler

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Rated impulse voltage		V_{IOTM}			8	kV
Safety temperature		T_{si}			150	$^{\circ}\text{C}$

Insulation Rated Parameters

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Partial discharge test voltage - Routine test	100 %, $t_{\text{test}} = 1 \text{ s}$	V_{pd}	1.6			kV
Partial discharge test voltage - Lot test (sample test)	$t_{\text{Tr}} = 60 \text{ s}$, $t_{\text{test}} = 10 \text{ s}$, (see figure 2)	V_{IOTM}	8			kV
		V_{pd}	1.3			kV
Insulation resistance	$V_{\text{IO}} = 500 \text{ V}$	R_{IO}	10^{12}			Ω
	$V_{\text{IO}} = 500 \text{ V}$, $T_{\text{amb}} = 100^\circ\text{C}$	R_{IO}	10^{11}			Ω
	$V_{\text{IO}} = 500 \text{ V}$, $T_{\text{amb}} = 150^\circ\text{C}$ (construction test only)	R_{IO}	10^9			Ω

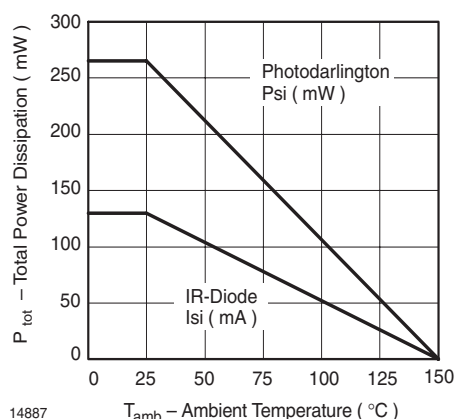


Figure 1. Derating diagram

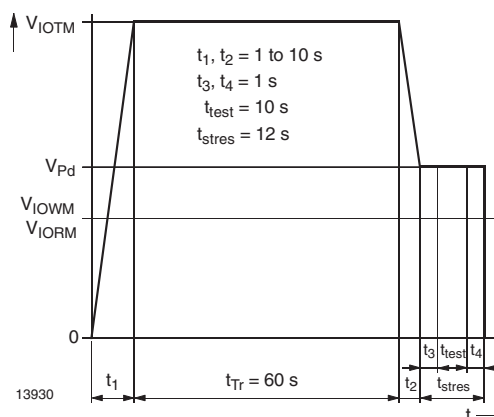


Figure 2. Test pulse diagram for sample test according to DIN EN 60747-5-2(VDE0884)/ DIN EN 60747-; IEC60747

Switching Characteristics

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Rise time	$V_{\text{CC}} = 2 \text{ V}$, $I_{\text{C}} = 10 \text{ mA}$, $R_{\text{L}} = 100 \Omega$ (see figure 3)	t_{r}		300		μs
Fall time	$V_{\text{CC}} = 2 \text{ V}$, $I_{\text{C}} = 10 \text{ mA}$, $R_{\text{L}} = 100 \Omega$ (see figure 3)	t_{f}		250		μs

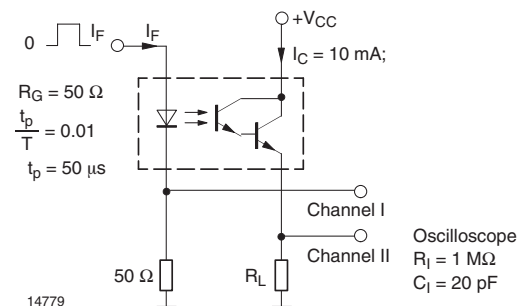


Figure 3. Test circuit, non-saturated operation

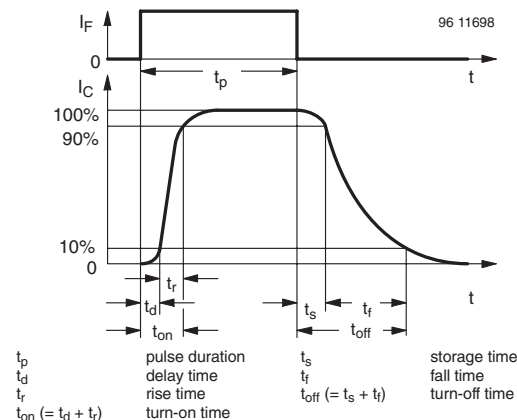


Figure 4. Switching Times

Typical Characteristics ($T_{amb} = 25^{\circ}\text{C}$ unless otherwise specified)

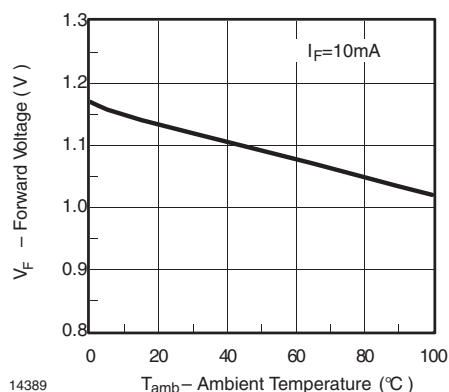


Figure 5. Forward Voltage vs. Ambient Temperature

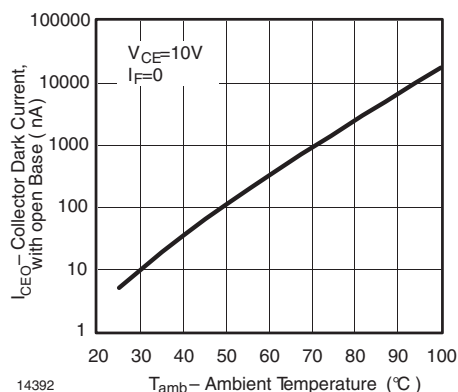


Figure 8. Collector Dark Current vs. Ambient Temperature

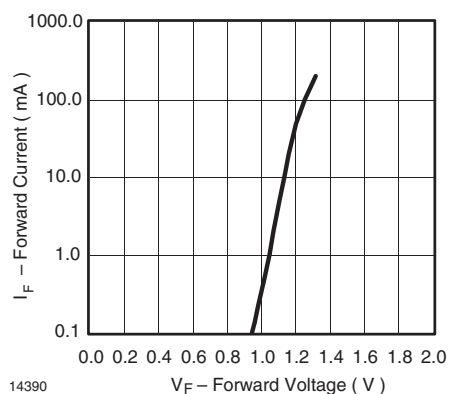


Figure 6. Forward Current vs. Forward Voltage

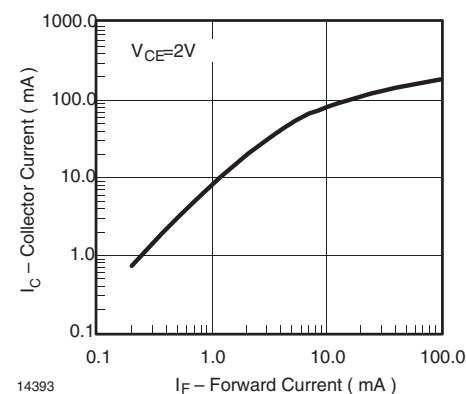


Figure 9. Collector Current vs. Forward Current

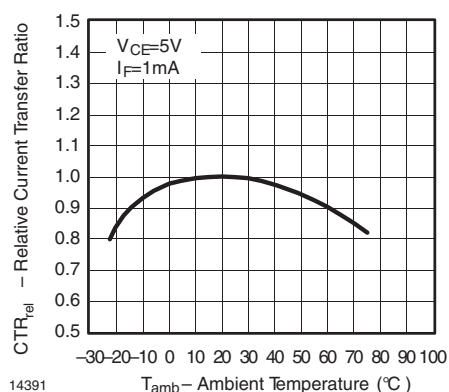


Figure 7. Relative Current Transfer Ratio vs. Ambient Temperature

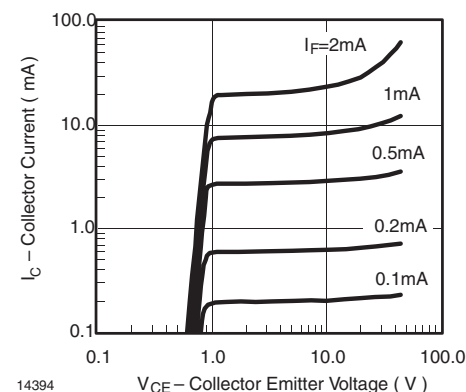


Figure 10. Collector Current vs. Collector Emitter Voltage

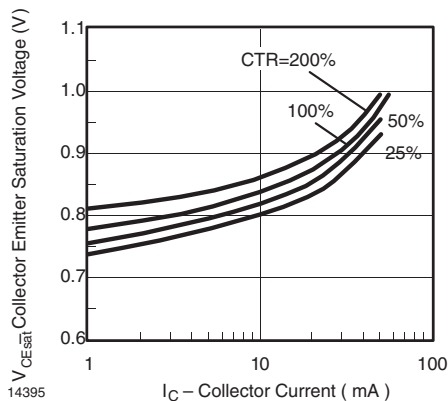


Figure 11. Collector Emitter Saturation Voltage vs. Collector Current

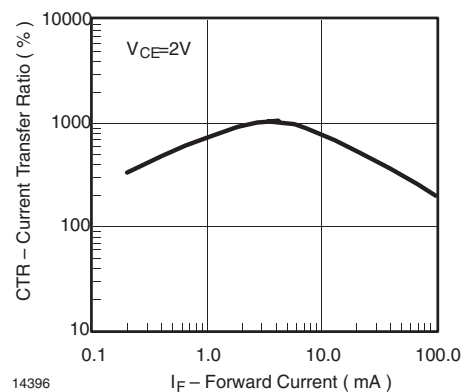
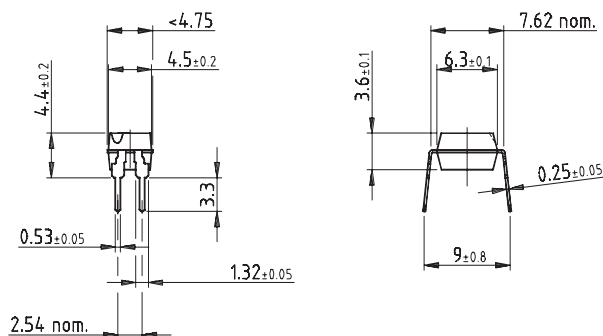
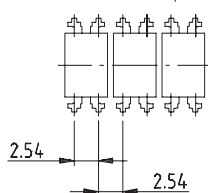


Figure 12. Current Transfer Ratio vs. Forward Current

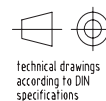
Package Dimensions in mm



E.g.:
special Features: endstackable
to 2.54mm (.100") spacing



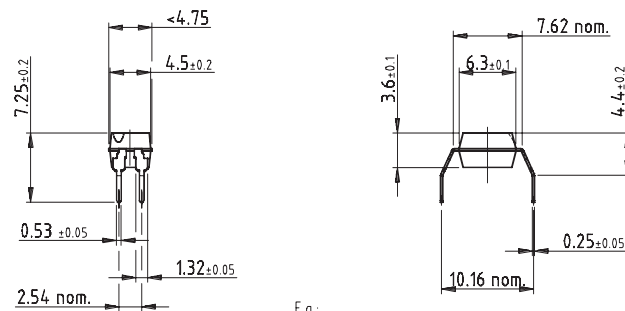
weight : ca 0.25g
creepage distance : > 6mm
air path : > 6mm
after mounting on PC board



Drawing-No.: 6.544-5302.03-4
Issue: 5, 20.03.02

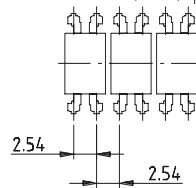
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Package Dimensions in mm



weight : ca 0.25g
 creepage distance : > 8mm
 air path : > 8mm
 after mounting on PC board

E.g.:
 special Features: endstackable
 to 2.54mm (.100") spacing



technical drawings
 according to DIN
 specifications

Drawing-No.: 6.544-5303.03-4

Issue: 4; 20.03.02

14792



Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design
and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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